- Install label in silk screened box after final wash. Text shall be 8 pt. font. Text shall be per the Label Table in the PDF schematic.
- These assemblies are ESD sensitive, ESD precautions shall be observed.
- These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- Place SH-11 on J3 and SH-12 on J5 (pins 1-2)
- Component BL1 must be assembled to U6. Before U5 is attached to the board.
- Remove protective coverings from BL1 and U5
- Slide pins of U5 into holes of BL1. BL1 must lie flat on the back of U5.
- Solder U5 - BL1 assembly to the board.
- Solder Pins 1, 2, 3, 10, 19, and 20 of U5 to BL1 from the top to insure electrical continuity.
- U8 is to be inserted into the holes for J4 and J6 through J20 with U8 Pin 1 in J4

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE | BOARD #: ISE4014 | REV: E3 | SUN REV: Not In VersionControl
---|---|---|---
IGNORE -> Top Overlay | TIDA-00213
PLOT NAME = Top Assembly Drawing | GENERATED : 10/23/2014 1:13:57 PM | TEXAS INSTRUMENTS
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